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(12) **United States Design Patent**  
**Uemura et al.**

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(54) **UPPER CHAMBER FOR A PLASMA  
PROCESSING APPARATUS**

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(\*) Notice: This patent is subject to a terminal dis-  
claimer.

(\*\*) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (11) Cl.** ..... **13-03**

(52) **U.S. Cl.**

USPC ..... **D13/182**; D15/138

(58) **Field of Classification Search**

USPC ..... D13/182; D15/138

See application file for complete search history.

(56) **References Cited**

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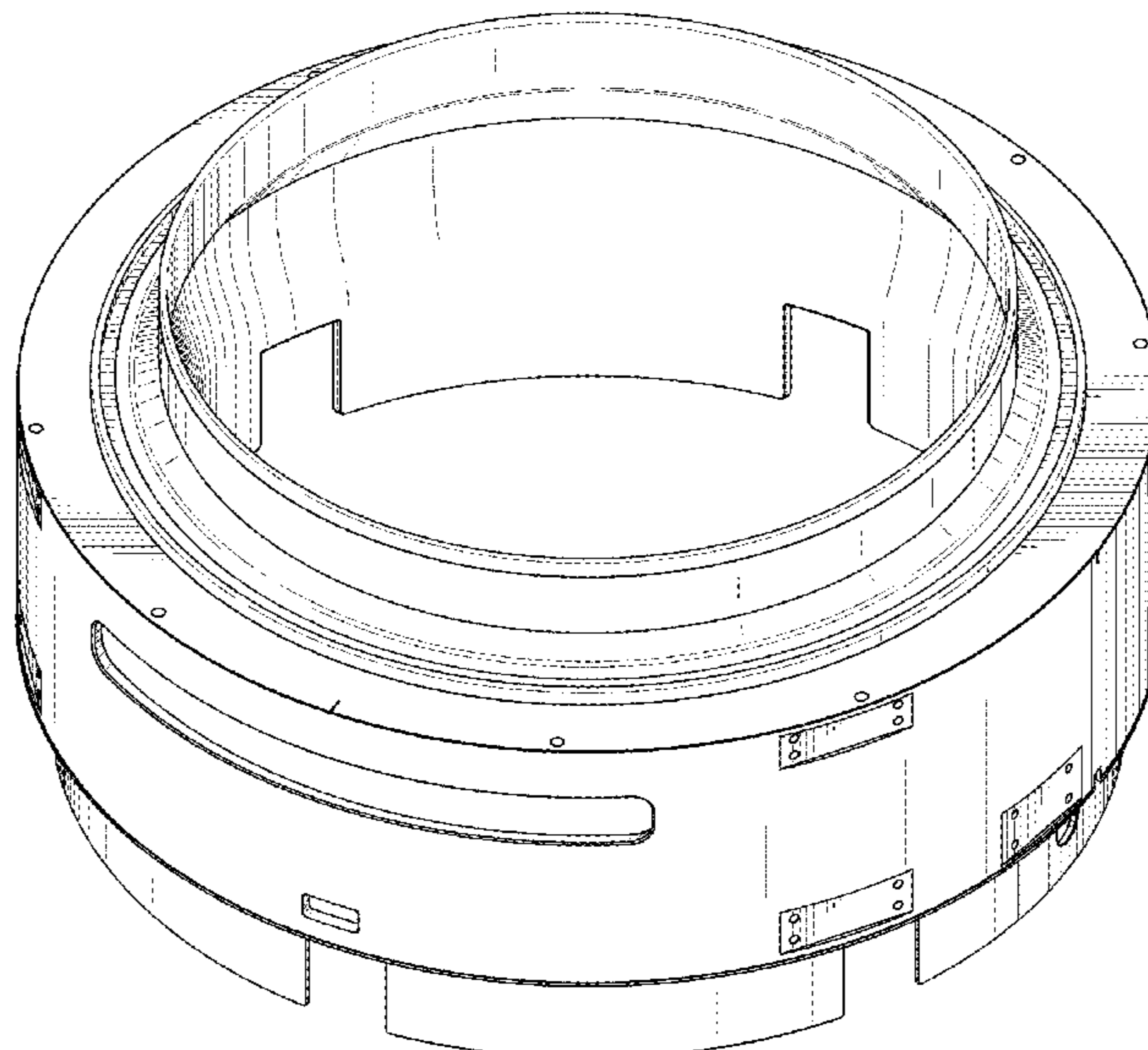
(57) **CLAIM**

The ornamental design for an upper chamber for a plasma processing apparatus, as shown and described.

**DESCRIPTION**

FIG. 1 is a front and top perspective of an upper chamber for a plasma processing apparatus according to the design; FIG. 2 is a front elevational view thereof; FIG. 3 is a rear elevational view thereof; FIG. 4 is a right side elevational view thereof; FIG. 5 is a left side elevational view thereof; FIG. 6 is a top plan view thereof; FIG. 7 is a bottom plan view thereof; FIG. 8 is a cross-sectional view taken along line 8-8 of FIG. 6; and, FIG. 9 is a partially enlarged view taken along line 9-9 of FIG. 8.

**1 Claim, 6 Drawing Sheets**



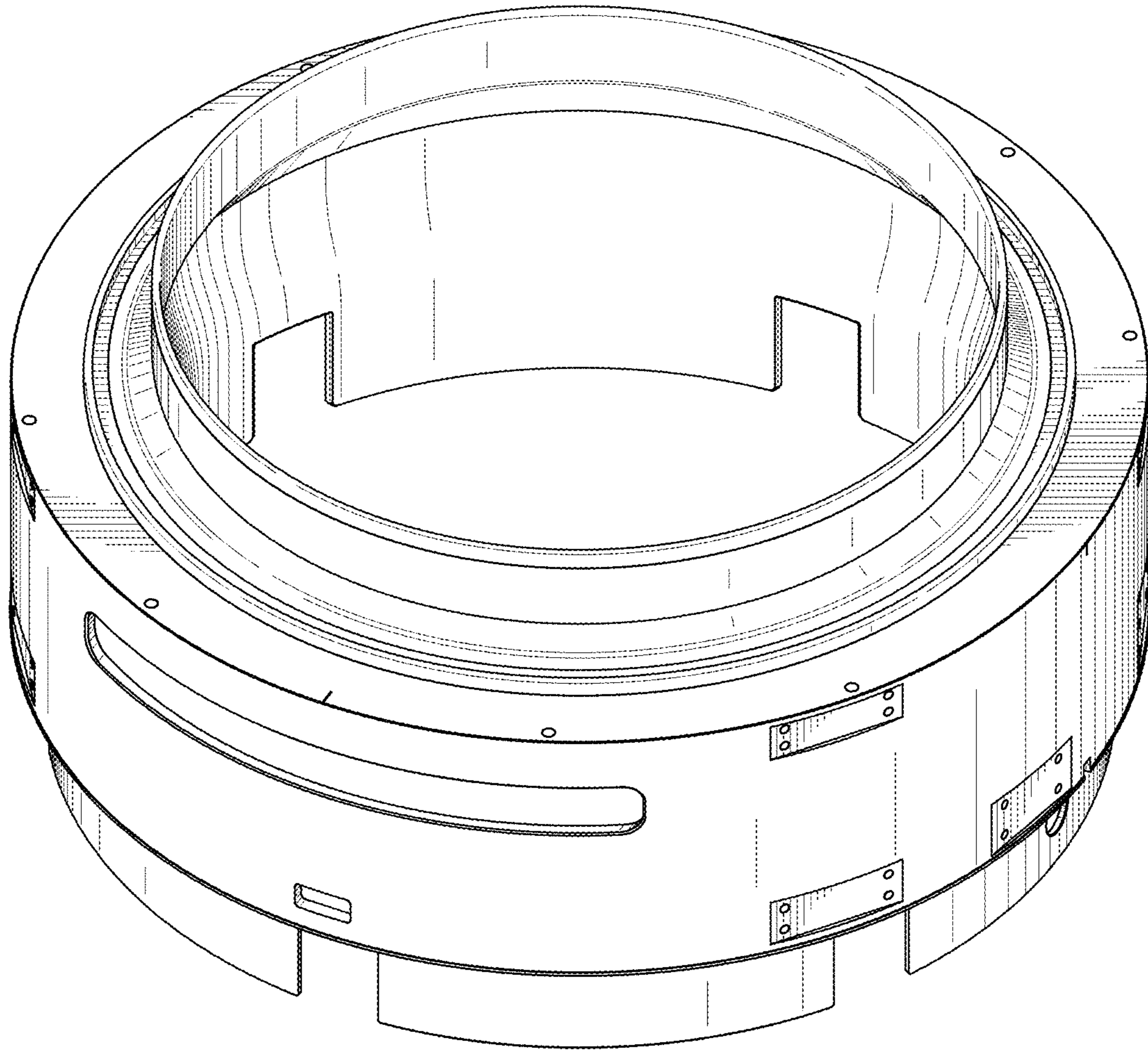


FIG. 1

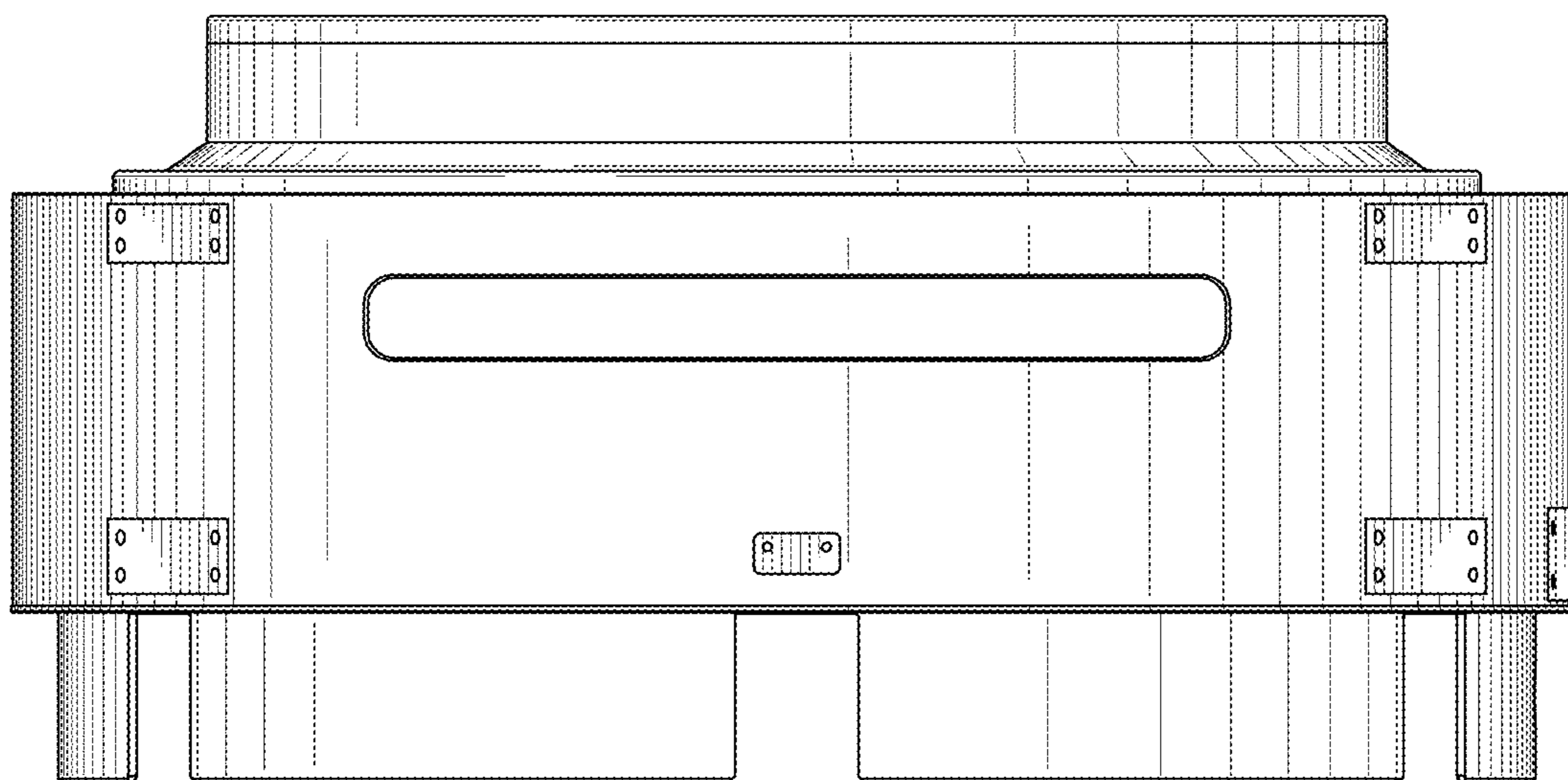


FIG. 2

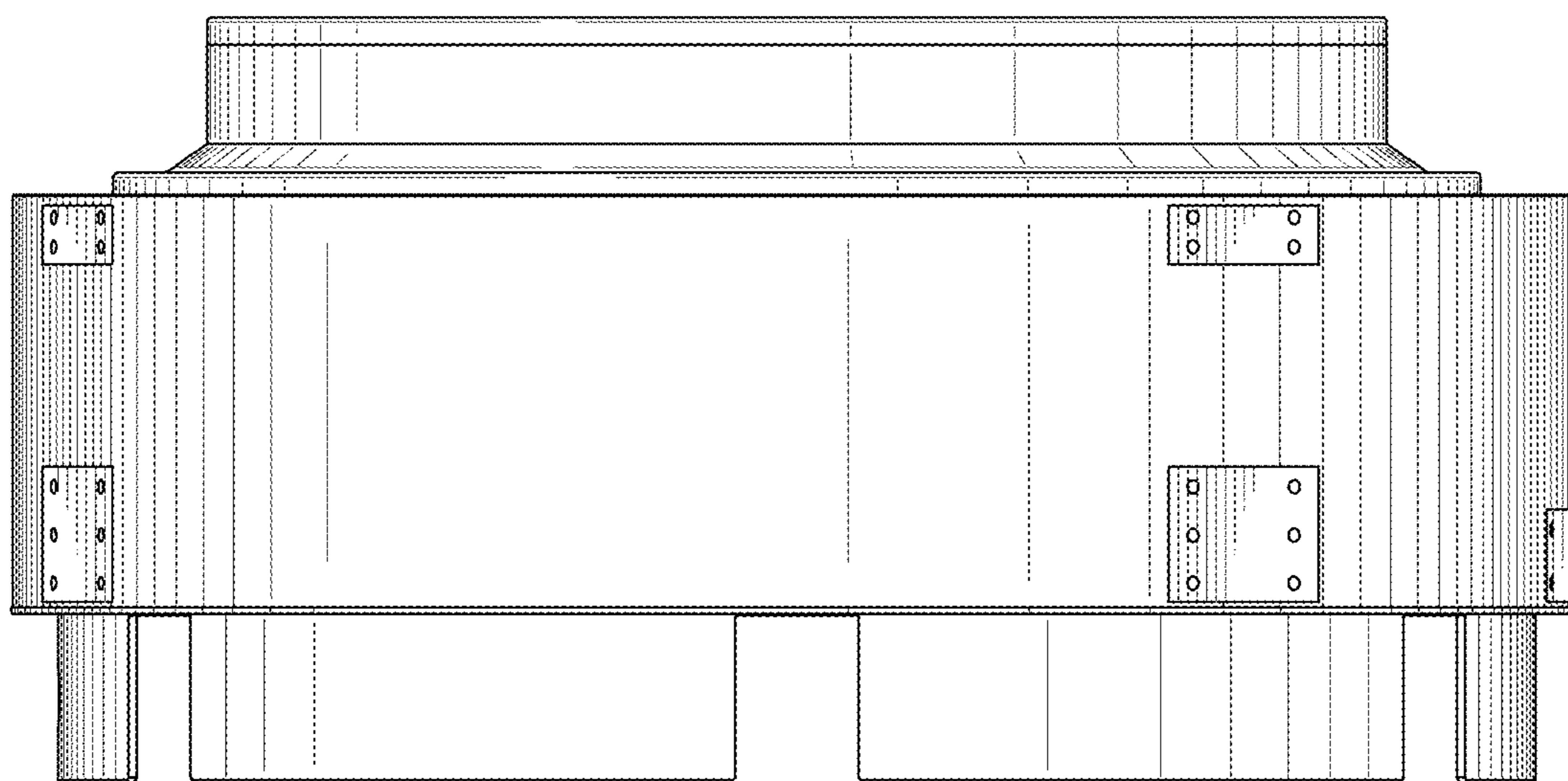
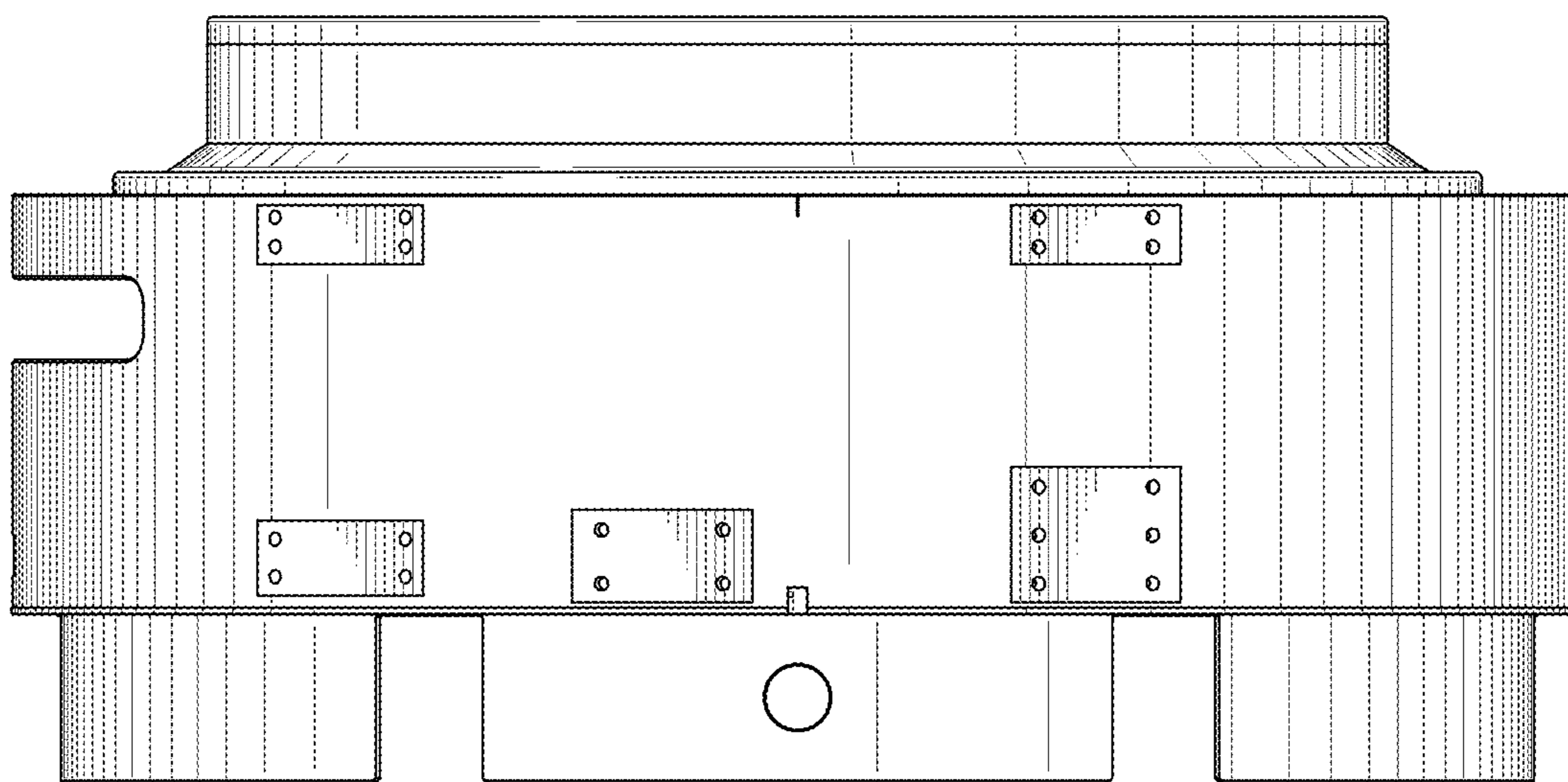
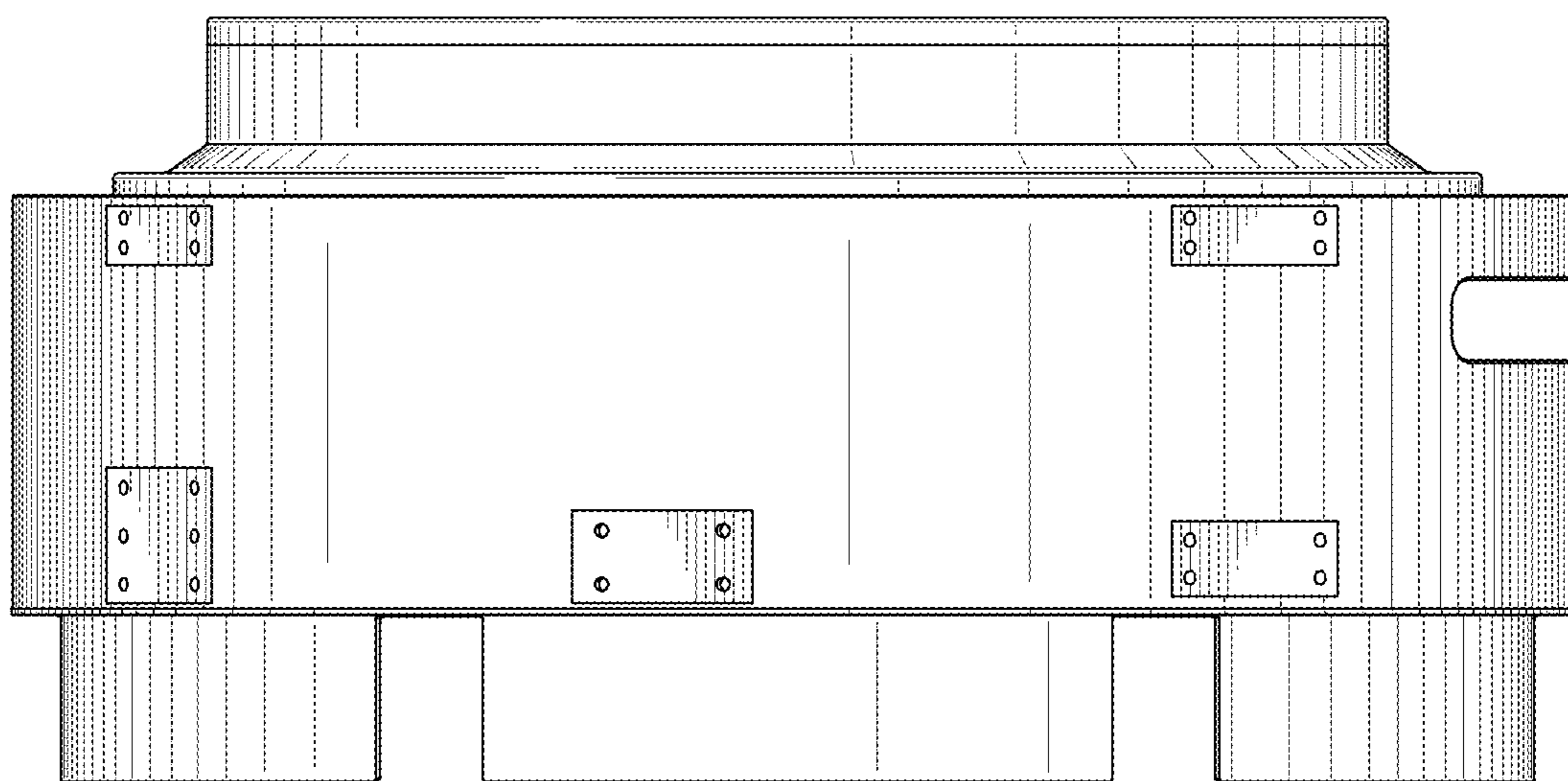


FIG. 3



*FIG. 4*



*FIG. 5*

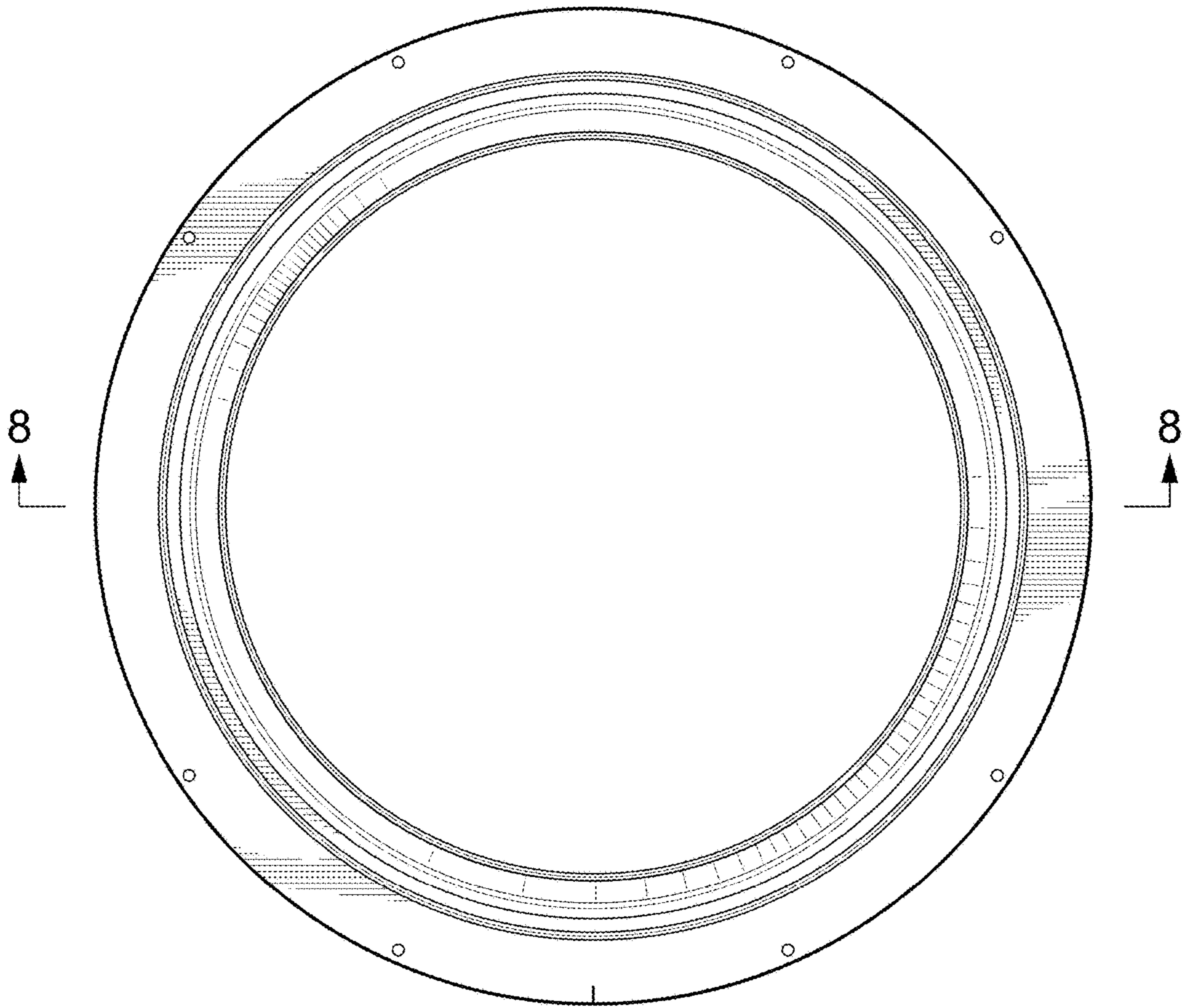
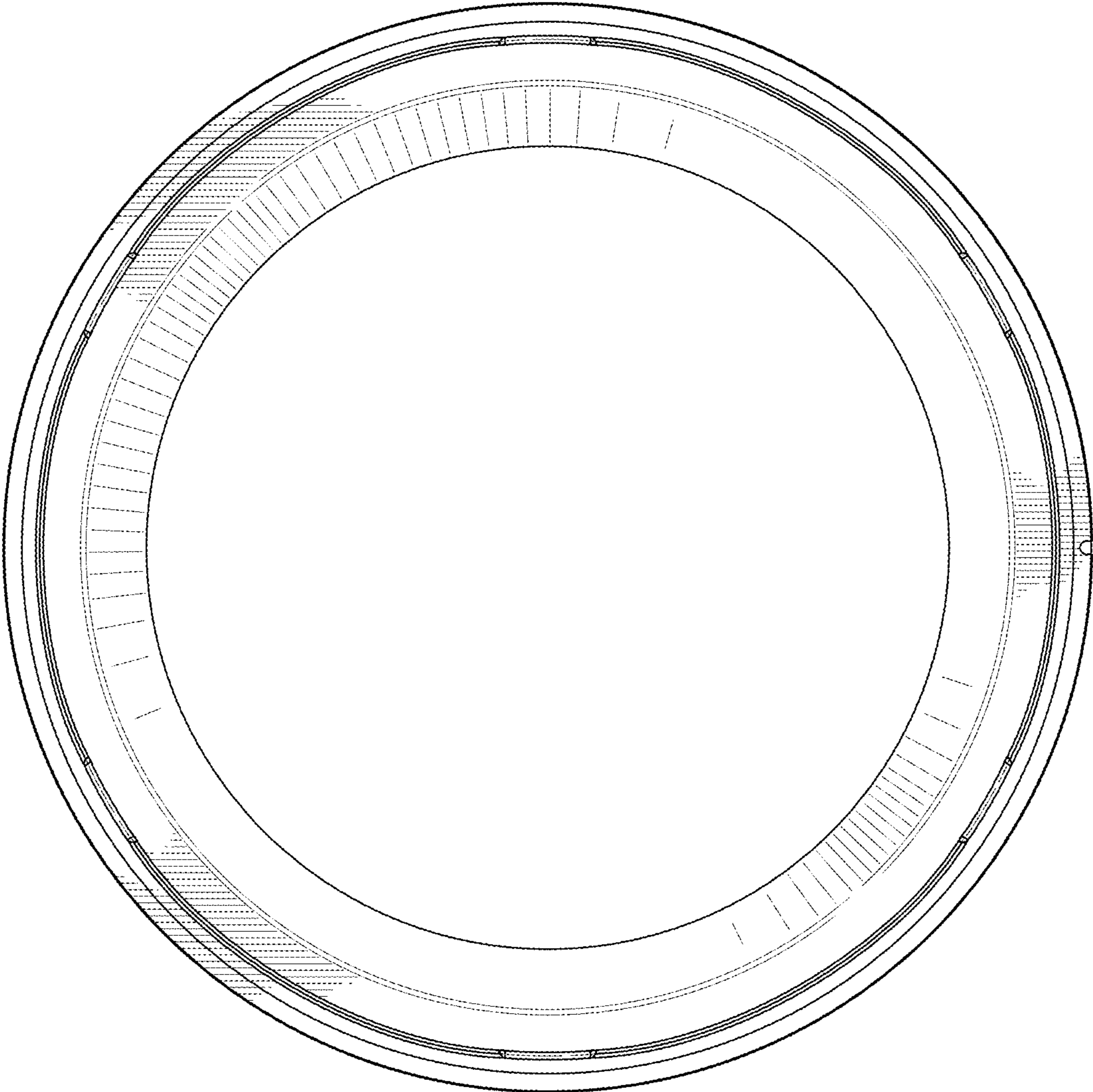


FIG. 6



**FIG. 7**

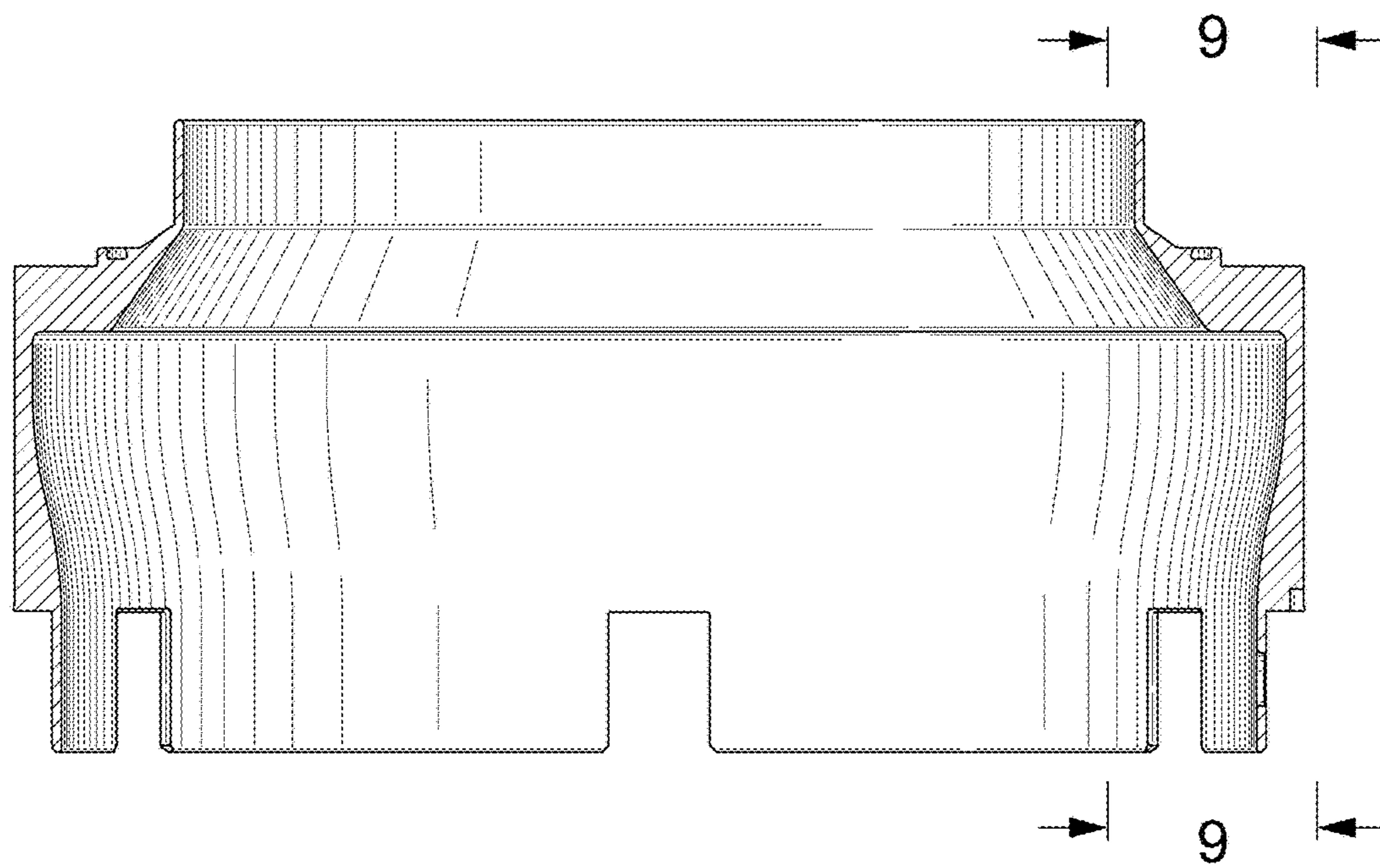


FIG. 8

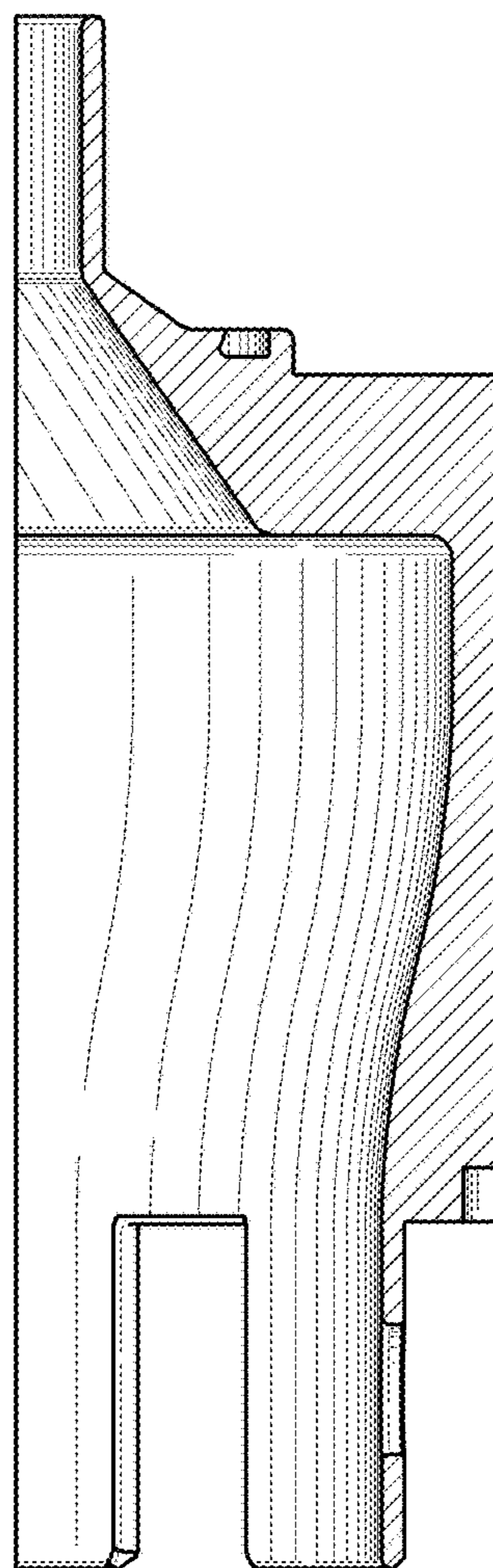


FIG. 9